

Wiring, Printed - Component

COMPANY

LEITON GMBH

Wolframstr. 96
BERLIN, 12105 Germany

E348420

Type	Cond Width			Cond Thk mic	Max		Report			Max		Meets UL796 Class	C DSR	I	
	Min mm	Edge mm	SS/ DS/ DSO		Area Diam mm	date After 2022-01-01	Surface Mount Technology	Assembly Process Temp °C	Solder Process Cycles	Solder Limits °C sec	Oper Temp °C				
Mass laminated (multilayered) printed wiring boards															
L-4	0.1	0.2	17	DS	38	No	-	-	-	280	20	130	V-0	All	-
YF-4	0.06	0.18	17	DS	50.8	No	-	-	-	280	20	130	V-0	All	3
Multilayer printed wiring boards															
FI-M	0.10	0.10	17 Int:68	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
KB-04	0.07	0.1	12 Int:102	DS	76.2	No	-	-	-	288	20	130	V-0	All	*
KB-05	0.10	0.10	17 Int:68	DS	50.8	No	-	-	-	288	10	130	V-0	All	3
KB-07	0.17	0.17	17 Int:34	DS	50.8	No	-	-	-	260	10	130	V-0	All	0
KB-08	0.4	0.4	17 Int:204	DS	50.8	No	-	-	-	288	10	130	V-0	All	*
ME-M4	0.08	0.08	9 Int:102.9	DS	25.4	No	-	-	-	288	10	130	V-0	All	3
ME-M7	0.08	0.08	9 Int:140	DS	50.8	No	-	-	-	288	10	130	V-0	All	3
RI-5	0.08	0.08	18 Int:105	DS	63.5	No	-	-	-	280	20	120	V-0	All	*
VF-M	0.08	0.08	17 Int:70	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
YF-7	0.075	0.18	17 Int:68	DS	50.8	No	-	-	-	280	20	130	V-0	All	*
YF-M (ASP 1)	0.06	0.18	17 Int:68	DS	50.8	Yes	Yes	260	3	-	-	130	V-0	All	*
Multilayer printed wiring boards, flammability only Recognition															
ME-M4-1	-	-	-	DS	-	No	-	-	-	288	10	-	V-0	-	-
ME-M7-1	-	-	-	DS	-	No	-	-	-	288	10	-	V-0	-	-
Single Layer Metal Base Printed Wiring Board															
YF-5	0.13	0.2	34	SS	50.8	No	-	-	-	288	10	125	V-0	-	2
Single Layer Metal Base Printed Wiring Board, flammability only Recognition															
YF-6	-	-	-	SS	-	No	-	-	-	288	10	-	V-0	-	-
Single Layer Metal Base Printed Wiring Boards															
RI-7	0.17	0.18	34	SS	63.5	No	-	-	-	288	20	120	V-0	-	0
Single layer printed wiring boards															
FI-D	0.10	0.10	17	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
KB-01	0.08	0.11	17	DS	76.2	No	-	-	-	288	20	130	V-0	All	*
KB-06	0.15	0.17	17	DS	50.8	No	-	-	-	260	10	130	V-0	All	0
ME-S6	0.08	0.08	9	DS	25.4	No	-	-	-	288	10	130	V-0	All	3

ME-S7	0.08	0.08	9	DS	50.8	No	-	-	-	288	10	130	V-0	All	3
ME-S8	0.08	0.08	9	DS	25.4	No	-	-	-	288	10	130	V-0	All	3
RI-2	0.05	0.15	33	DS	50.8	No	-	-	-	280	10	105	V-0	All	*
RI-3	0.15	0.45	33	DS	50.8	No	-	-	-	280	10	120	V-0	All	3
RI-6	0.08	0.08	18	DS	63.5	No	-	-	-	280	20	120	V-0	All	*
VF-D	0.08	0.08	17	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
YF-1	0.1	0.1	17	DS	50.8	No	-	-	-	288	20	130	V-0	All	3
YF-2 (ASP 1)	0.06	0.18	17	DS	50.8	Yes	Yes	260	3	-	-	130	V-0	All	*
YF-3	0.075	0.18	17	DS	50.8	No	-	-	-	280	20	130	V-0	All	*
Single layer printed wiring boards, flammability only Recognition															
ME-S7-1	-	-	-	DS	-	No	-	-	-	288	10	-	V-0	-	-

* - CTI marking is optional and may be marked on the printed wiring board.

(ASP 1) - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company name or trademark  ,  ,  ,  or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

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